

**THE INDUSTRIAL DEVELOPMENT AUTHORITY
 LAND CLEARANCE FOR REDEVELOPMENT AUTHORITY
 OR THE PLANNED INDUSTRIAL EXPANSION AUTHORITY
 OF THE CITY OF ST. LOUIS, MISSOURI**

APPLICATION FOR BOND REFUNDING

I. BACKGROUND INFORMATION

A. Borrower* _____ Contact Person _____
 Address _____ Phone _____
 City _____ State _____ Zip Code _____

B. Is the Borrower a: Corporation Partnership Proprietorship

C. Is the Borrower's Business: Manufacturing Non Manufacturing
 Residential Other (specify) _____

D. Were the original bonds issued by the:
 The Industrial Development Authority
 Planned Industrial Expansion Authority
 Land Clearance for Redevelopment Authority
 Other (Specify) _____

E.

	Firm Name	Contact Person	Phone
Original Bond Purchaser (or Marketing/Remarketing Agent) _____	_____	_____	_____
Borrower's Counsel _____	_____	_____	_____
Letter of Credit (or other Security) Provider _____	_____	_____	_____

II. PROJECT INFORMATION

A. Type of Bond (Multi-Family, TIF), etc. _____
B. Outstanding Bond Balance \$ _____
C. Current Interest Rate \$ _____
D. Current Maturity Date _____
E. Current Amortization Schedule _____

 * Legal Name of Borrowing Entity for this Project

F. For manufacturers only:

1. Outstanding term will be extended Yes No

If Yes, until what date: _____

III. ATTACHMENTS

The following must be submitted with the completed application:

Indicate if attached (X)

- | | | |
|--------------------------|---|---------------------|
| <input type="checkbox"/> | <u>Bond Trustee Information</u> | ATTACHMENT A |
| <input type="checkbox"/> | <u>Narrative describing project, need for Refinancing, Realized Impacts, and Future Impacts (including jobs and Leveraged Investment)</u> | ATTACHMENT B |
| <input type="checkbox"/> | <u>Letter of Credit or Other Security Commitment</u>
A preliminary letter of commitment from a financial institution providing security for the bonds, Commitment or Underwriting Letter | ATTACHMENT C |
| <input type="checkbox"/> | <u>Financial Information</u> (Financial Statement, Pro forma) | |
| <input type="checkbox"/> | <u>\$2,000 check</u> payable to the appropriate refunding entity (see Revised Fee Schedule) | |
| <input type="checkbox"/> | The Industrial Development Authority | |
| <input type="checkbox"/> | Land Clearance for Redevelopment Authority | |
| <input type="checkbox"/> | Planned Industrial Expansion Authority | |

The undersigned acknowledges receipt of the Authority's current Schedule of Charges for Bond-related services and hereby agrees to pay all such fees and expenses in an amount at such time as stipulated therein.

Dated: _____, 20__

Borrower

Borrower's Representative – Name and Title

Application should be filed with:

The Industrial Development Authority of the City of St. Louis
c/o St. Louis Development Corporation
1520 Market Street, Suite 2000
St. Louis, Missouri 63103-2630
(314) 657-3700

Note: A complete fee schedule is attached.

**SCHEDULE OF CHARGES FOR BOND-RELATED SERVICES
OF THE INDUSTRIAL DEVELOPMENT AUTHORITY AND
THE PLANNED INDUSTRIAL EXPANSION AUTHORITY**

REFUNDING BONDS

Fees due at time of re-issuance of bonds is one-half of one percent of the face amount of the bond.

NEW BONDS

Fees due at a time of issuance of new bonds is one-half of one percent of the face amount of the bond.

Note: A \$2,000 non-refundable application fee is due upon submission of an application for both refunding and new bonds.

Borrower will also be responsible for all costs of advertising, which are legally required by Missouri tax-exempt bond legislation.

ATTACHMENT "A"

BOND TRUSTEE INFORMATION RELEASE

To Whom It May Concern:

_____ hereby authorize(s) its current bond trustee to release payment and related information pertaining to the undersigned to _____ (bond counsel). Such information may be released exclusively to personnel of the bond counsel.

Date: _____

Bond Obligor

ATTACHMENT “B”

NARRATIVE DESCRIBING PROJECT

**(Need for Refinancing, Realized Impacts, and Future Impacts
(including jobs and Leveraged Investment))**

ATTACHMENT "C"

LETTER OF CREDIT OR OTHER SECURITY COMMITMENT